



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

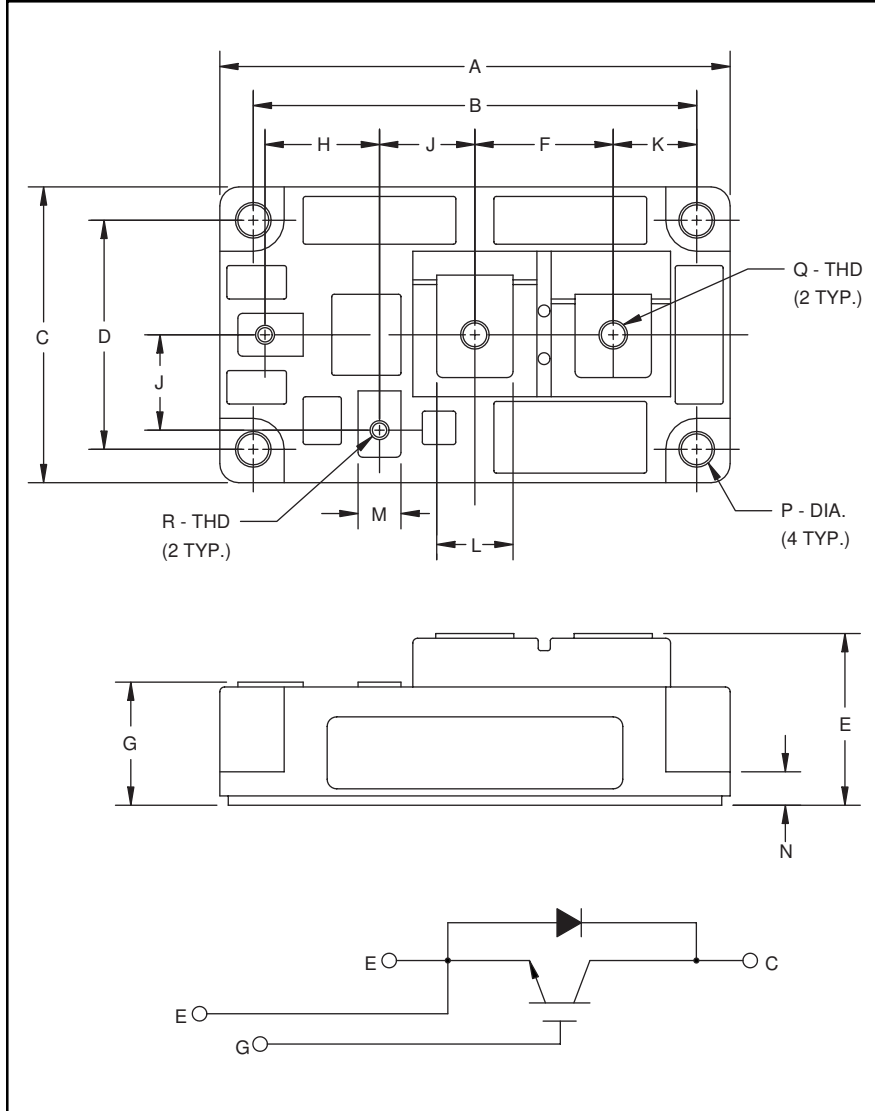
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



### Single IGBTMOD™ H-Series Module 400 Amperes/1200 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.21	107.0
B	3.661±0.01	93.0±0.25
C	2.44	62.0
D	1.89±0.01	48.0±0.25
E	1.42+0.04/-0.02	36.0+1.0/-0.5
F	1.14	29.0
G	1.02+0.04/-0.2	25.8+1.0/-0.5
H	0.94	24.0

Dimensions	Inches	Millimeters
J	0.79	20.0
K	0.69	17.5
L	0.63	16.0
M	0.35	9.0
N	0.28	7.0
P	0.26 Dia.	Dia. 6.5
Q	M6 Metric	M6
R	M4 Metric	M4



#### Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of one IGBT Transistor in a single configuration with a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

#### Features:

- Low Drive Power
- Low  $V_{CE(sat)}$
- Discrete Super-Fast Recovery (135ns) Free-Wheel Diode
- High Frequency Operation (20-25kHz)
- Isolated Baseplate for Easy Heat Sinking

#### Applications:

- AC Motor Control
- Motion/Servo Control
- UPS
- Welding Power Supplies
- Laser Power Supplies

#### Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM400HA-24H is a 1200V ( $V_{CES}$ ), 400 Ampere Single IGBTMOD™ Power Module.

Type	Current Rating Amperes	$V_{CES}$ Volts (x 50)
CM	400	24

**CM400HA-24H**  
**Single IGBTMOD™ H-Series Module**  
 400 Amperes/1200 Volts

**Absolute Maximum Ratings,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

Ratings	Symbol	CM400HA-24H	Units
Junction Temperature	$T_j$	-40 to 150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage (G-E SHORT)	$V_{CES}$	1200	Volts
Gate-Emitter Voltage	$V_{GES}$	$\pm 20$	Volts
Collector Current	$I_C$	400	Amperes
Peak Collector Current	$I_{CM}$	800*	Amperes
Diode Forward Current	$I_F$	400	Amperes
Diode Forward Surge Current	$I_{FM}$	800*	Amperes
Power Dissipation	$P_d$	2800	Watts
Max. Mounting Torque M6 Terminal Screws	-	26	in-lb
Max. Mounting Torque M6 Mounting Screws	-	26	in-lb
Module Weight (Typical)	-	400	Grams
V Isolation	$V_{RMS}$	2500	Volts

\* Pulse width and repetition rate should be such that device junction temperature does not exceed the device rating.

**Static Electrical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	1.0	mA
Gate Leakage Current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	0.5	$\mu\text{A}$
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 40\text{mA}, V_{CE} = 10V$	4.5	6.0	7.5	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 400A, V_{GE} = 15V$	-	2.5	3.4**	Volts
		$I_C = 400A, V_{GE} = 15V, T_j = 150^\circ\text{C}$	-	2.25	-	Volts
Total Gate Charge	$Q_G$	$V_{CC} = 600V, I_C = 400A, V_{GS} = 15V$	-	2000	-	nC
Diode Forward Voltage	$V_{FM}$	$I_E = 400A, V_{GS} = 0V$	-	-	3.4	Volts

\*\* Pulse width and repetition rate should be such that device junction temperature rise is negligible.

**Dynamic Electrical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

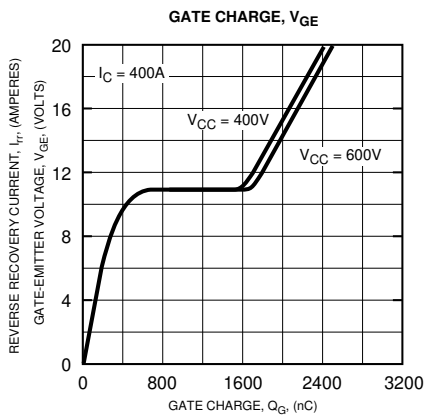
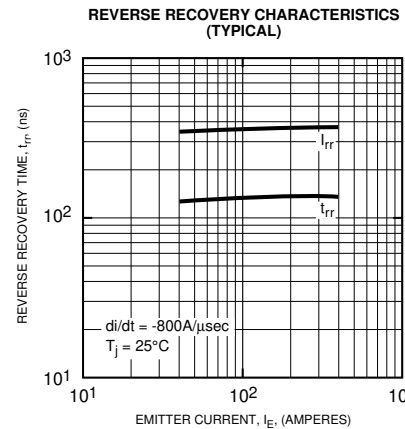
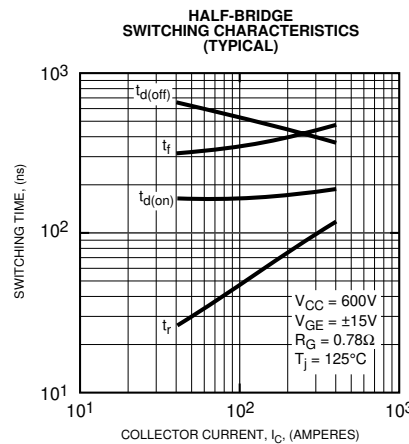
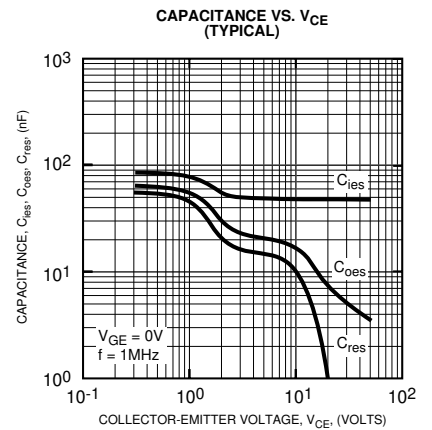
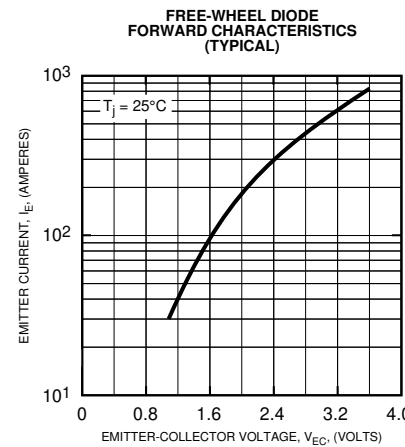
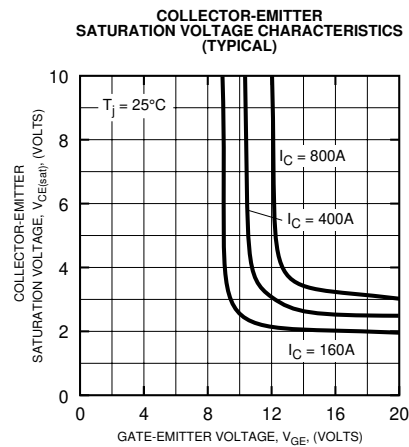
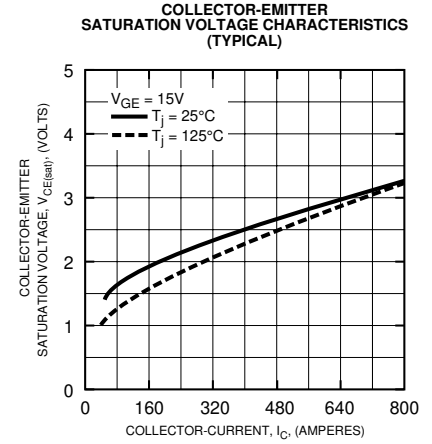
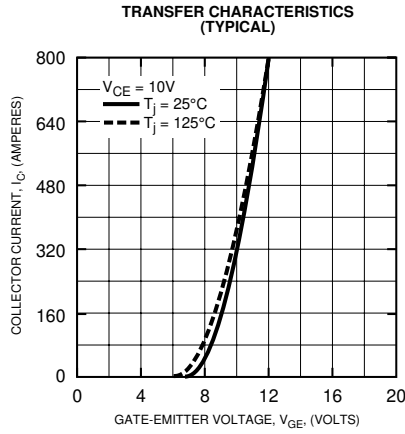
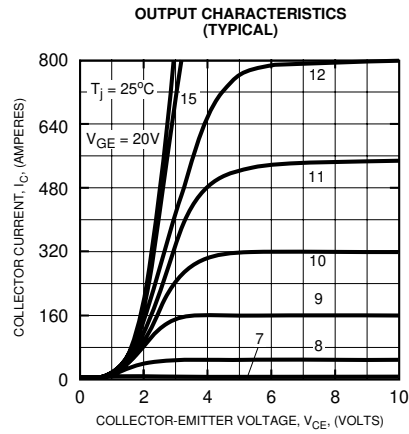
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance	$C_{ies}$		-	-	80	nF
Output Capacitance	$C_{oes}$	$V_{GE} = 0V, V_{CE} = 10V, f = 1\text{MHz}$	-	-	28	nF
Reverse Transfer Capacitance	$C_{res}$		-	-	16	nF
Resistive	Turn-on Delay Time	$V_{CC} = 600V, I_C = 400A$	-	-	300	ns
Load	Rise Time					
Switching	Turn-off Delay Time	$V_{GE1} = V_{GE2} = 15V, R_G = 0.78\Omega$	-	-	350	ns
	Times					
Diode Reverse Recovery Time	$t_{rr}$	$I_E = 400A, di_E/dt = -800A/\mu\text{s}$	-	-	250	ns
Diode Reverse Recovery Charge	$Q_{rr}$	$I_E = 400A, di_E/dt = -800A/\mu\text{s}$	-	2.97	-	$\mu\text{C}$

**Thermal and Mechanical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per IGBT	-	-	0.045	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per FWDi	-	-	0.09	$^\circ\text{C/W}$
Contact Thermal Resistance	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	-	-	0.040	$^\circ\text{C/W}$



**CM400HA-24H**  
**Single IGBTMOD™ H-Series Module**  
 400 Amperes/1200 Volts



**CM400HA-24H**  
**Single IGBTMOD™ H-Series Module**  
 400 Amperes/1200 Volts

